

## SCHOTTKY BARRIER RECTIFIERS

### Features

- Metal silicon junction, majority carrier conduction
- Guarding for overvoltage protection
- Low power loss, high efficiency
- High current capability
- low forward voltage drop
- High surge capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications



Weight : 17mg , 0.0006 oz

Simplified outline SOD-123FL and symbol

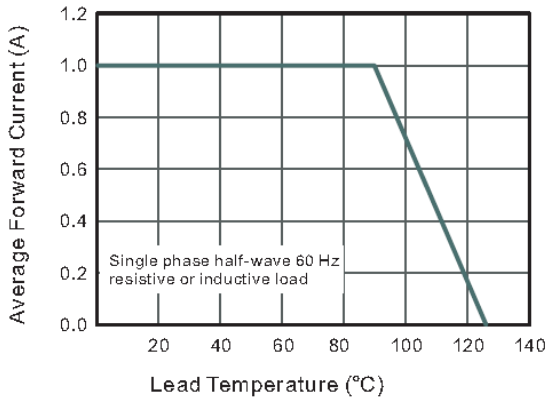
PIN	DESCRIPTION
1	Cathode
2	Anode

### Maximum Ratings and Electrical characteristics

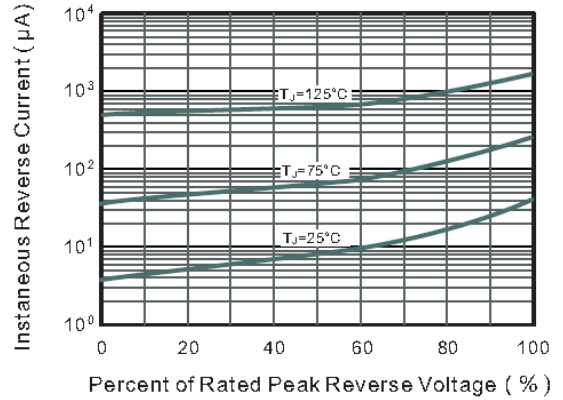
Ratings at 25 °C ambient temperature unless otherwise specified.

Parameter	Symbols	SK1020	SK1030	SK1040	Units
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	20	30	40	V
Maximum RMS voltage	$V_{RMS}$	14	21	28	V
Maximum DC Blocking Voltage	$V_{DC}$	20	30	40	V
Maximum Average Forward Rectified Current 0.375" (9.5 mm) Lead Length at $T_L = 90^\circ\text{C}$	$I_{F(AV)}$	1			A
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed On Rated Load (JEDEC method) at $T_L = 70^\circ\text{C}$	$I_{FSM}$	25			A
Maximum Instantaneous Forward Voltage at 1 A Maximum Instantaneous Forward Voltage at 3.1 A	$V_F$	0.45 0.75	0.55 0.875	0.6 0.9	V
Maximum Instantaneous Reverse Current at $T_A = 25^\circ\text{C}$ Rated DC Reverse Voltage $T_A = 100^\circ\text{C}$	$I_R$	1 10			mA
Typical Thermal Resistance	$R_{\theta JA}$ $R_{\theta JL}$	50 15			$^\circ\text{C/W}$
Typical Junction Capacitance	$C_j$	110			pF
Storage and Operating Junction Temperature Range	$T_J, T_{stg}$	-55 ~ +125			$^\circ\text{C}$

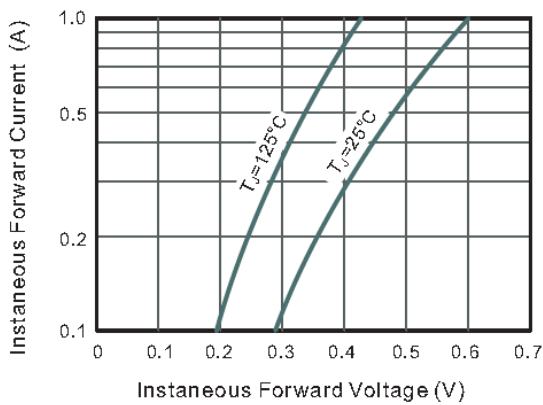
**Fig.1 Forward Current Derating Curve**



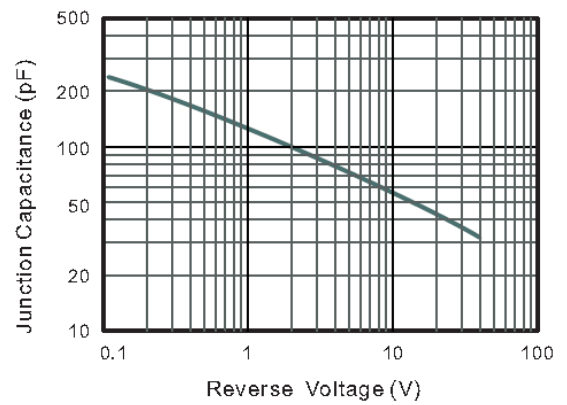
**Fig.2 Typical Reverse Characteristics**



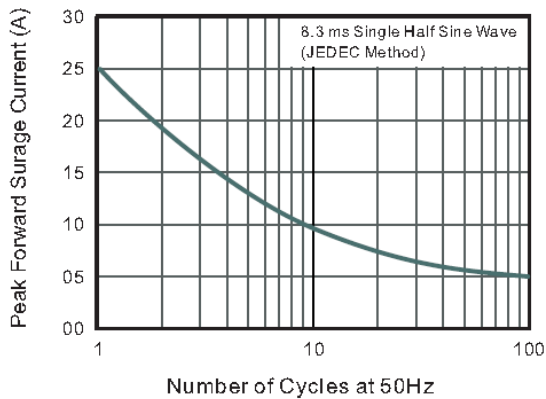
**Fig.3 Typical Forward Characteristic**



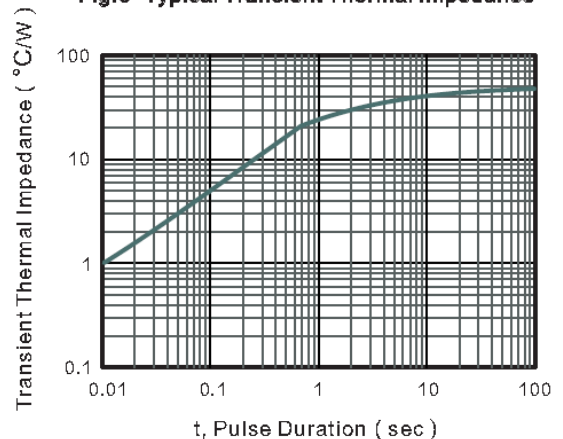
**Fig.4 Typical Junction Capacitance**



**Fig.5 Maximum Non-Repetitive Peak Forward Surge Current**



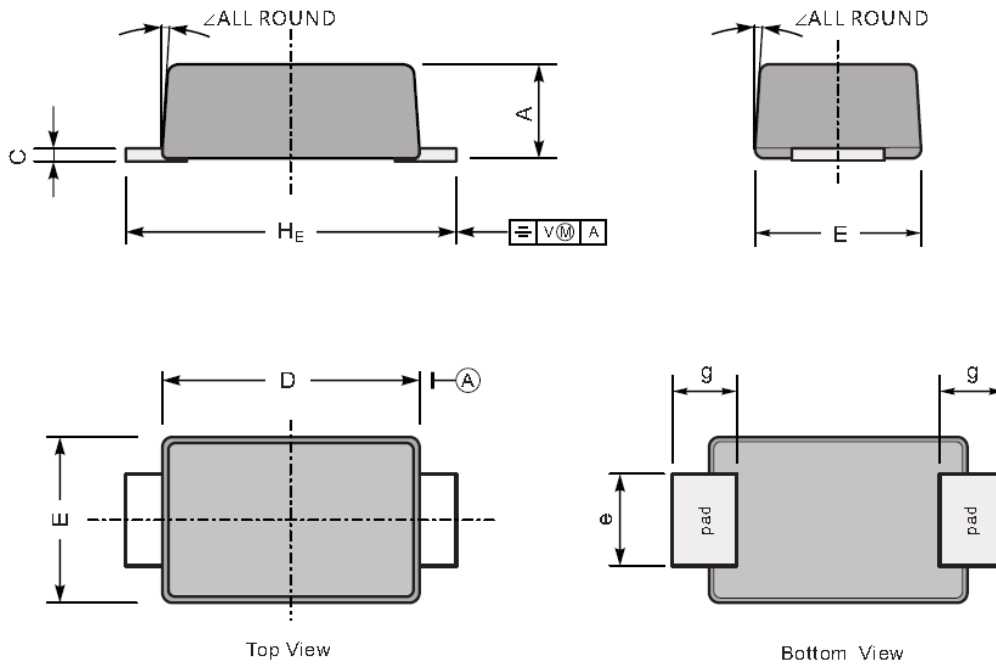
**Fig.6- Typical Transient Thermal Impedance**



## PACKAGE OUTLINE

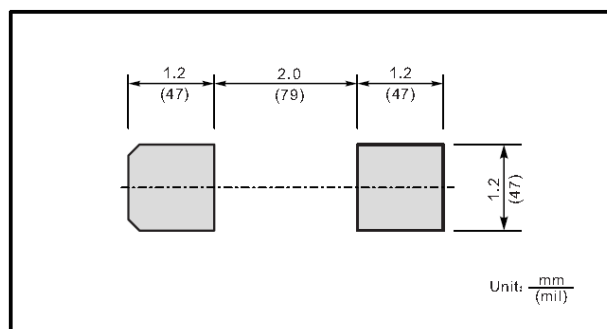
Plastic surface mounted package; 2 leads

SOD123FL

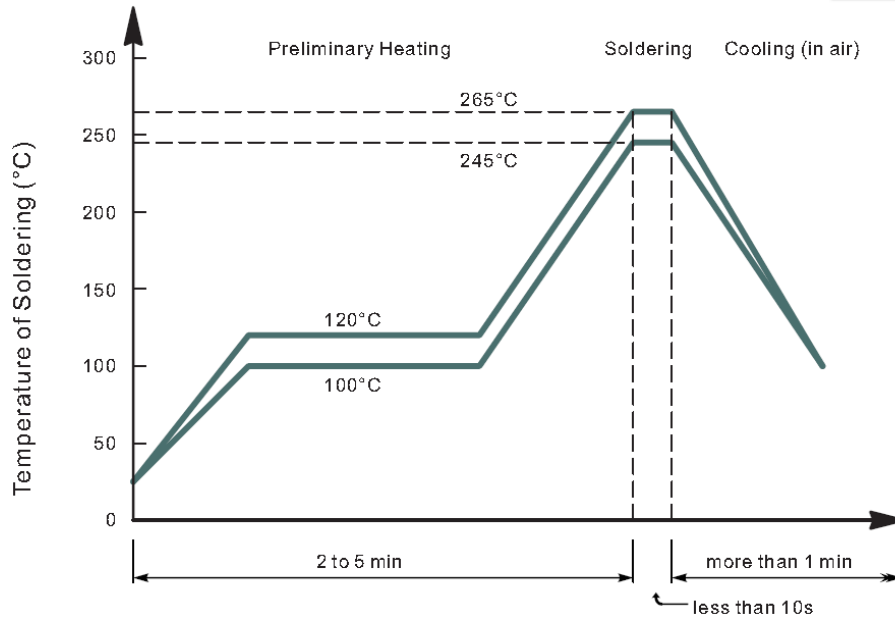


UNIT		A	C	D	E	e	g	$H_E$	$\angle$
mm	max	1.1	0.20	2.9	1.9	1.1	0.9	3.8	7°
	min	0.9	0.12	2.6	1.7	0.8	0.7	3.5	
mil	max	43	7.9	114	75	43	35	150	
	min	35	4.7	102	67	31	28	138	

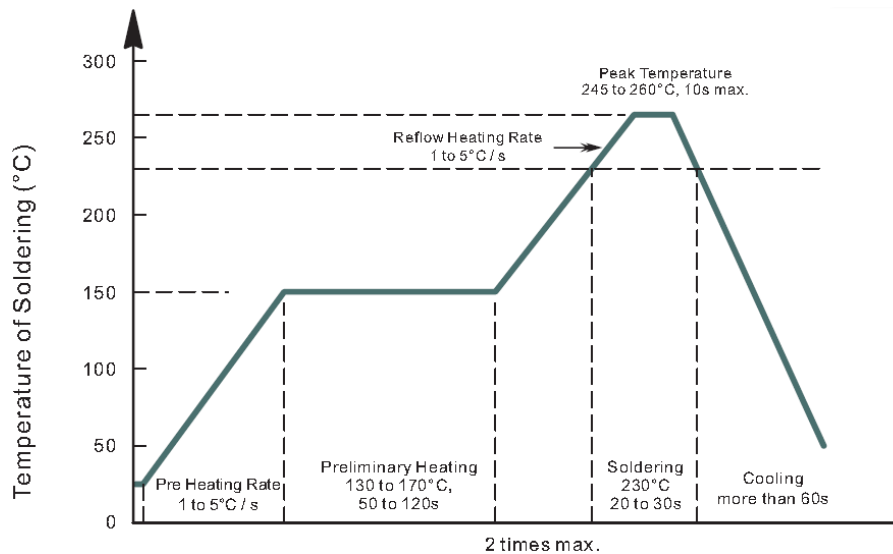
### The recommended mounting pad size



## • Recommended condition of flow soldering



## • Recommended condition of reflow soldering



Recommended peak temperature is over 245 °C. If peak temperature is below 245 °C, you may adjust the following parameters; time length of peak temperature (longer), time length of soldering (longer), thickness of solder paste (thicker)

• Condition of hand soldering: Temperature: 320°C / Time: 3s max. / Times: one time

• Remark:

Lead free solder paste (96.5Sn/3.0Ag/0.5Cu)